

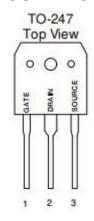
GENERAL DESCRIPTION

This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

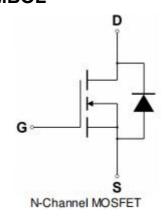
FEATURES

- ◆ Robust High Voltage Termination
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a Discrete Fast Recovery Diode
- ◆ Diode is Characterized for Use in Bridge Circuits
- ♦ I_{DSS} and V_{DS}(on) Specified at Elevated Temperature
- Isolated Mounting Hole Reduces Mounting Hardware

PIN CONFIGURATION



SYMBOL



ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain to Current — Continuous	I _{D 25C(1)}	71.9	
	I _{D 100C(1)}	45.5	Α
- Pulsed	I_{DM}	215.8	
Gate-to-Source Voltage — Continue	V_{GS}	±30	V
Total Power Dissipation-TO-247		581	W
TO-3P		595	
	P_D		
Derate above 25°C −TO-247		4.65	W/°C
TO-3P		4.76	
Junction and Storage Temperature Range	T_J , T_{STG}	-55 to 150	$^{\circ}\!\mathbb{C}$
Single Pulse Drain-to-Source Avalanche Energy $-T_\mathtt{J}$ = 25 $^\circ \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \! \!$	2725	m l	
$(V_{DD} = 100V, V_{GS} = 10V, I_L = 17A, L = 20mH, R_G = 25\Omega)$	E _{AS}	2725	mJ
Thermal Resistance — Junction to Case -TO-247	θјс	0.21	
Junction to CaseTO-3P			°C/W
 Junction to Ambient TO-3P ,TO-247 	θ_{JA}	40	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T_L	260	$^{\circ}\!\mathbb{C}$

⁽¹⁾ Drain current limited by maximum junction temperature, TO-3P Package.



ORDERING INFORMATION

Part Number	TOP MARK	Part Number	Packing Mthod	Note
GWM72S60XN247(Note1)	GWM72S60	TO-247	Tube	
GWM72S60XN3P(Note1)	GWM72S60	TO-3P	Tube	

Note1: X : Suffix for Halogen Free Product,

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_J = 25^{\circ}C$.

			GWM72S60			
Characteristic		Symbol	Min	Тур	Max	Units
Drain-Source Breakdown Voltage (V_{GS} = 0 V, I_{D} = 250 μ A)		V _{(BR)DSS}	600			V
Drain-Source Leakage Current (V _{DS} =600 V, V _{GS} = 0 V)		I _{DSS}			10	uA
Gate-Source Leakage Current-Forward (V _{gsf} = 30 V, V _{DS} = 0 V)		Igssf			100	nA
Gate-Source Leakage Current-Reverse (V _{gsr} = - 30 V, V _{DS} = 0 V)		Igssr			100	nA
Gate Threshold Voltage $(V_{DS} = V_{GS}, I_{D} = 250 \mu A)$		$V_{\text{GS(th)}}$	2		4	V
Static Drain-Source On-Resistance (V _{GS} = 10 V, I _D = 25.4A) *		R _{DS(on)}			46	mΩ
Input Capacitance	0/ 400 \/ \/ \	C _{iss}		5447		pF
Output Capacitance	$(V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz})$	Coss		233		pF
Reverse Transfer Capacitance		Crss		23		pF
Turn-On Delay Time	$(V_{DD} = 300 \text{ V}, I_{D} = 72 \text{ A}, R_{G} = 25\Omega) *$	t _{d(on)}		45.4		ns
Rise Time		tr		111.1		ns
Turn-Off Delay Time		t _{d(off)}		155.7		ns
Fall Time		t _f		110		ns
Total Gate Charge	(V _{DS} = 480 V, I _D = 72 A, V _{GS} = 10 V)*	Qg		127.6		nC
Gate-Source Charge		Q_{gs}		33.9		nC
Gate-Drain Charge	VG3 10 V)	Q_{gd}		51.2		nC
SOURCE-DRAIN DIODE CHAR	ACTERISTICS					
Forward On-Voltage(1)	(L = 72 A	V _{SD}			1.5	V
Forward Turn-On Time	$(I_S = 72 \text{ A}, d_{IS}/d_t = 100 \text{A}/\mu\text{S})$	t _{on}		**		ns
Reverse Recovery Time		t _{rr}		210		ns

^{*} Pulse Test: Pulse Width $\leq\!300\mu\text{s},$ Duty Cycle $\leq\!2\%$

^{**} Negligible, Dominated by circuit inductance



TYPICAL ELECTRICAL CHARACTERISTICS

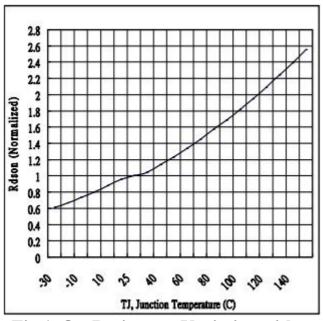


Fig 1. On-Resistance Variation with vs. Temperature

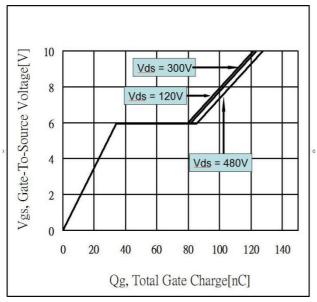


Fig 3. Typical Gate Charge vs. Gate-to-Source Voltage

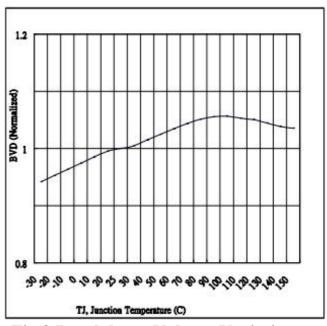


Fig.2 Breakdown Voltage Variation vs. Temperature

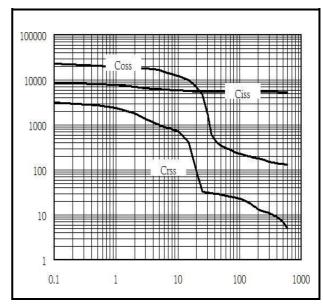


Fig 4. Typical Capacitance Vs. Drain-to-Source Voltage





Power Field Effect Transistor

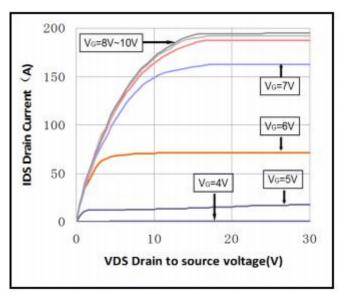


Fig 5. Typical Output Characteristics

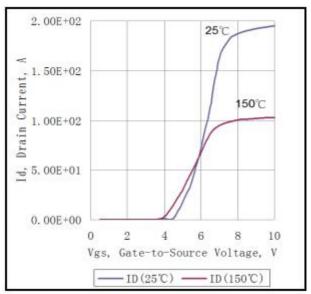


Fig 6. Typical Transfer Characteristics